

# φ0.25 ドリル加工事例

## φ0.25 Micro-Hole Drilling Performance

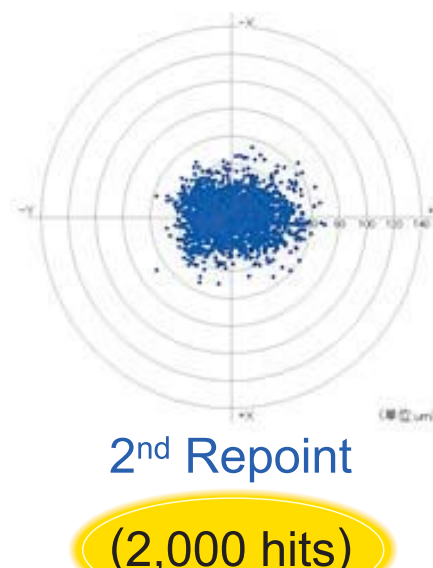
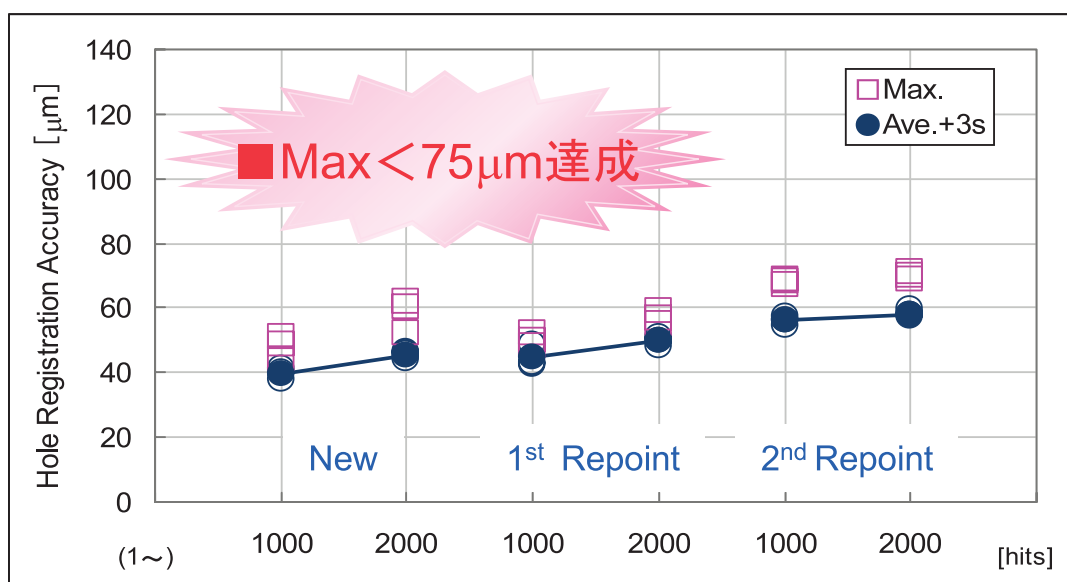
用途 半導体パッケージ用、ビルドアップ用内層コア材等 BGA、for HDI etc...

### 加工条件 [Drilling Condition]

Work Material : FR-4 R1566 t1.2(6 Layers) x 3 stacks  
 S : 160,000 min<sup>-1</sup> F : 2.8 m/min f : 17.5 μm/rev  
 Set Life : 2,000 hits x Repoint 2 times = Total 6,000 hits



### 穴位置精度 [Hole Registration Accuracy]



### 内壁粗さ [Hole Wall Quality at 2,000 hits]

■ 研磨後も驚愕の内壁品質

